



WBS 6.4.2.1

Liquid Argon Calorimeter Testing

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NSF Conceptual Design Review of the U.S. ATLAS HL-LHC Upgrade
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Bio-Sketch / Institute Overview

- Tim Andeen:
 - Assistant Prof. at UT-Austin, Fall-2015
 - ATLAS member since 2008
 - Fellow, CERN, 2008-2010; Postdoc, Columbia University, 2010-2015
 - LAr Phase 1 Upgrade Role:
 - Led testing of a new radiation-hard, high-speed Analog-to-Digital Converter (ADC) for Phase 1 Front-end upgrade (LTDB).
 - Searches for exotic new physics.
- UT-Austin
 - New ATLAS institution as of Feb, 2016 (previously 3 years as sub-institute of U. Chicago).
 - 2 professors (Peter Onyisi, TA)



Outline

- This talk – testing and performance of ASICS (ADC) and FEB2 boards.
 - ADC testing
 - Need and description
 - Work required – Performance and Irradiation
 - Experience from Phase 1
 - FEB2 testing
 - Need and description
 - Experience from original FEB
 - HASS testing
 - Workflow
 - [System Integration - DOE scope]



ASIC Testing

- Verify ADC functionality:
 - For novel ADC designs it is critical to verify performance of individual test chips and large batches. Can also provide feedback to R&D effort.
- Work split between performance testing (university) and irradiation testing (test beam facility).
 - Performance testing:
 - Precision, dynamic range, power consumption, noise and cross-talk, reliability (QA/QC).
 - Irradiation testing:
 - TID, NIEL, and SEE/SEU testing

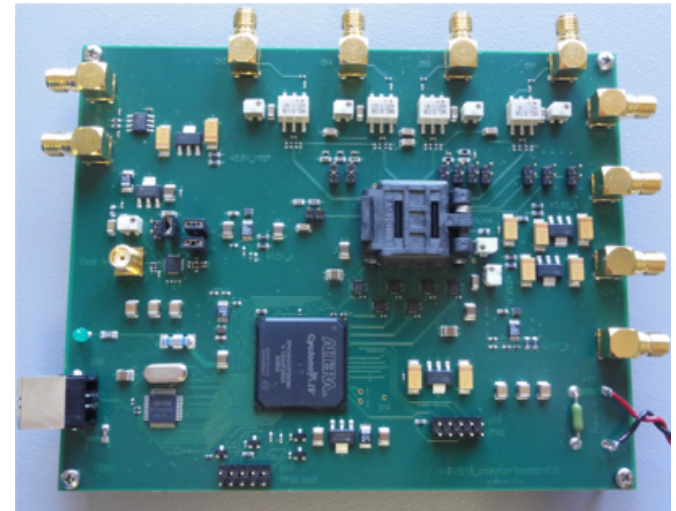


Characterizing ADC

- Sine-wave FFT method –industrial standard for ADC characterization.
- Typical parameters (figures of merit) for ADC characterization.
 - **SFDR** - Spurious Free Dynamic Range - Worst spurious value in the frequency spectrum w.r.t. the signal. For characterization the input signal is as close to the full range as possible.
 - **SINAD** - Signal to Noise And Distortion - The ratio of the signal amplitude to the root-sum-square of all spectral components, including harmonics. Generally, the SINAD gives the best indication of the ADC performance.
 - **ENOB** - Effective Number of Bits - Typically calculated by $\sim(\text{SINAD} - 1.76\text{dB})/6.02$.
 - **INL/DNL** - Integral/differential non-linearity - Difference between an actual step width and the ideal value (DNL) and the deviation of the actual transfer function from a straight line (INL).

ADC measurements

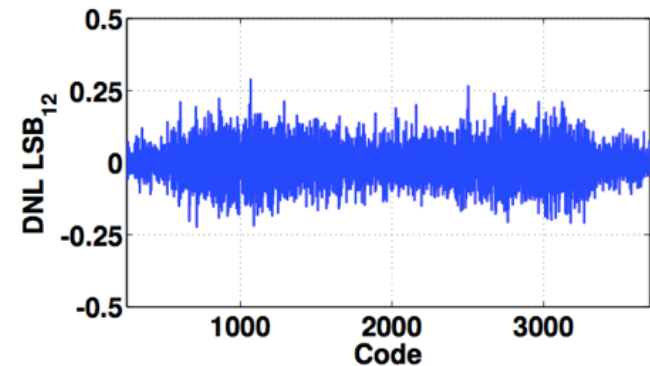
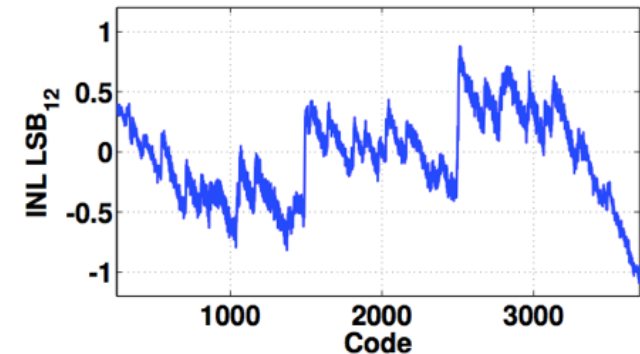
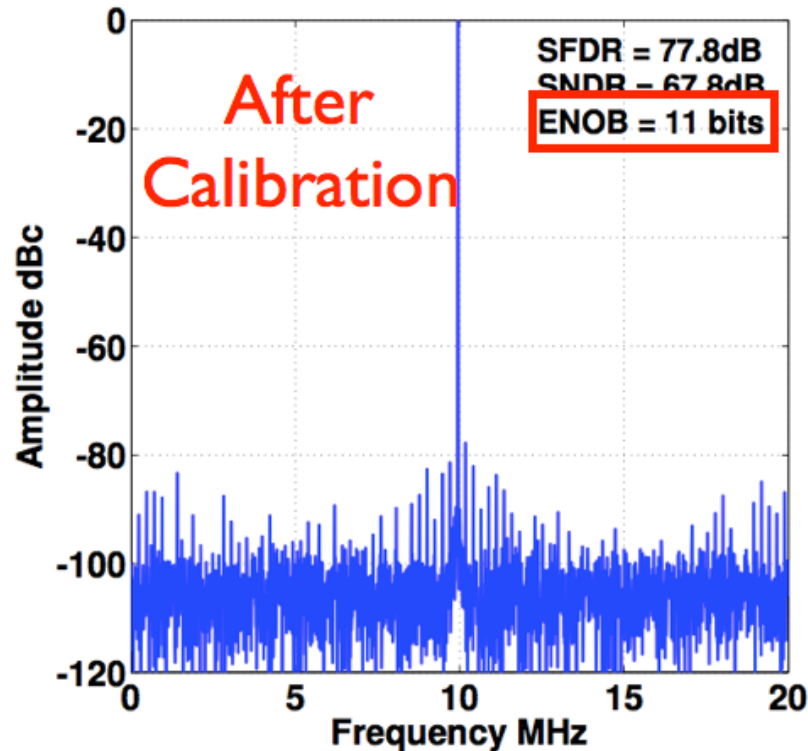
- Work involves performance measurements, as well as power consumption, noise and crosstalk between channels, prototype integration tests, and reliability (large batch testing), which will all be done at the university.
- Requires a test bench and PCBs (w/FPGA) designed to control/readout chip as well as DAQ and analysis software (physicist effort).





ADC Performance – Phase 1

- Example: Performance tests of ADC design for Phase 1.



- Experience from Phase 1 upgrade provides a guide for estimating effort.



Electronics Radiation Tolerance

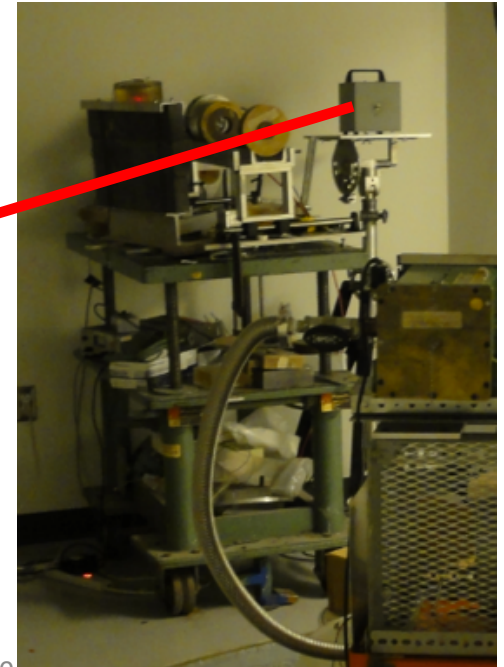
- ATLAS policy for HL-LHC radiation tolerances.
- Criteria set for three areas of concern:
 - TID (Total Ionizing Dose): cumulative over HL-LHC running
 - NIEL (Non-Ionizing Energy Loss): equivalent fluence of neutrons
 - SEE (Single Event Effect): transient effect, measured *in situ*.

Table 14. Radiation tolerance criteria of the LAr electronics for operation at HL-LHC for a total luminosity of 3000 fb^{-1} , including safety factors for background estimation, given in brackets. For COTS, an additional safety factor of 4 is included in case of production in unknown multiple lots. Furthermore, the ATLAS policy specifies annealing tests that allow reducing the enhanced low dose rate safety-factor to 1, which currently is set to 1.5 for ASICs and 5 for COTS.

	TID [kGy]	NIEL [$n_{\text{eq}}/\text{cm}^2$]	SEE [h/cm^2]
ASIC	0.75 (2.25)	2.0×10^{13} (2)	3.8×10^{12} (2)
COTS (multiple lots)	9.9 (30)	8.2×10^{13} (8)	1.5×10^{13} (8)
COTS (single-lot)	2.5 (7.5)	2.0×10^{13} (2)	3.8×10^{12} (2)
LVPS (EMB and EMEC)	0.58 (30)	9.2×10^{12} (8)	2.4×10^{12} (8)
LVPS (HEC)	0.17 (2.25)	4.7×10^{12} (2)	2.7×10^{11} (2)

Radiation measurements

- Work involves irradiation testing at test-beam facilities (e.g. protons at Mass. Gen. Hospital, neutrons at LANCE facility at Los Alamos) for measurement of TID, NIEL and SEE/SEU sensitivity.
- Requires specially designed PCBs + FPGA software as well as remote DAQ and analysis software.



ADC Irradiation– Phase 1

- Phase 1 ADC radiation tests with proton beams digitizing at 40 MHz.
- Guided by Phase 1 experience for estimates of effort required.
- Tools from Phase 1 will be adapted to HL-LHC.

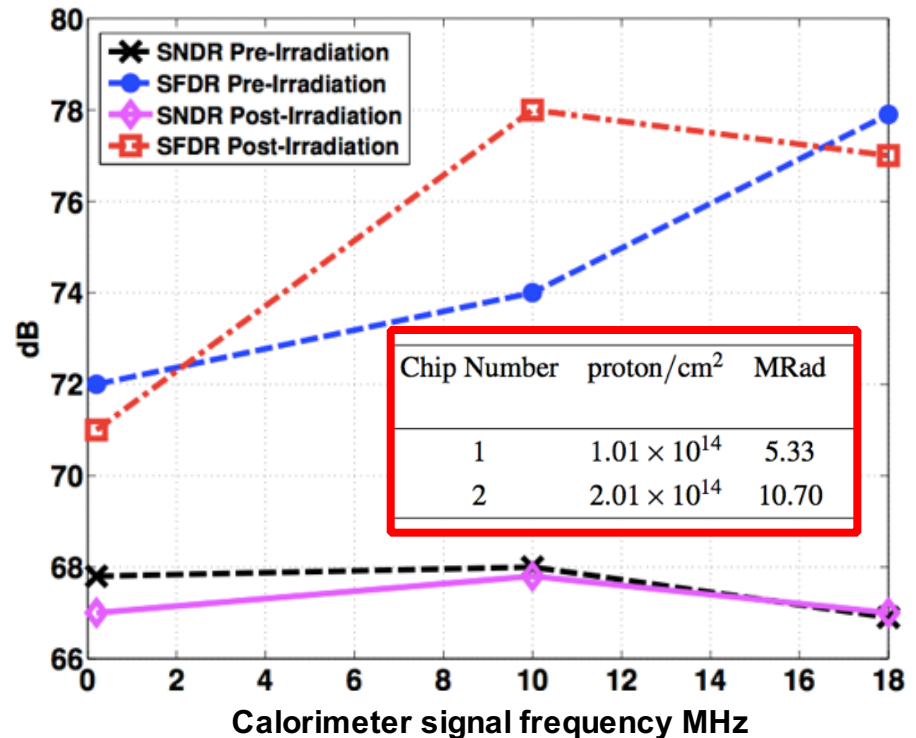


Table 2: Measurements of ADC SEE performance in a 227 MeV proton beam.

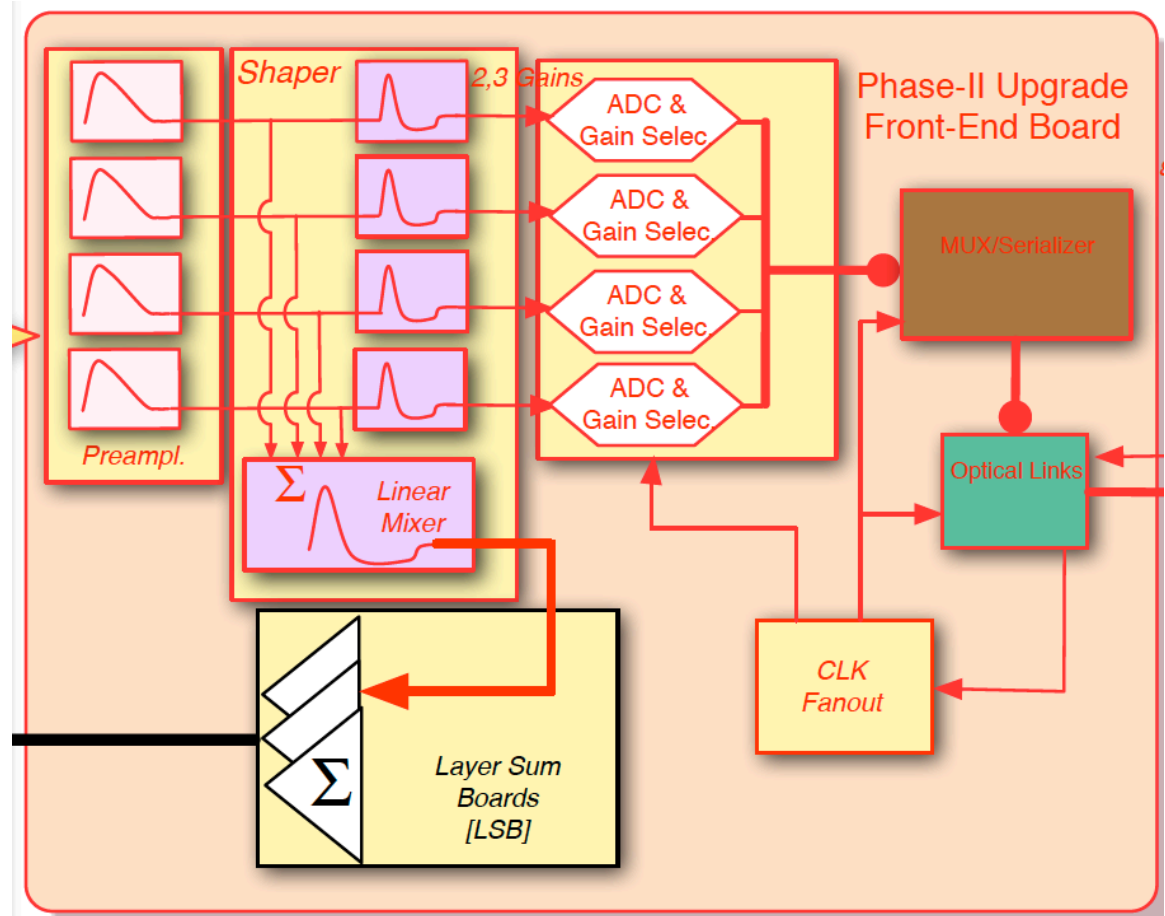
Chip No.	Rate [10 ⁸ proton/cm ² /s]	Dose [kRad]	SEFI	SEU (analog)	SEU (digital)	SEE	Cross section (w/analog errors) [10 ⁻¹² cm ²]
3	19.0	101	0	8	1	12	0.6 (5.1 ± 1.8)
3	76.0	283	0	41	2	43	0.6 (9.8 ± 1.5)
4	18.6	203	1	10	0	11	0.3 (3.5 ± 1.1)

FEB2 Testing

- With custom ASICs, plus the mixed analog-digital nature of the FEB2, develop custom test setup and procedures.

- Many Radiation-tolerant (65 nm) ASICs

- Preamplifier/shaper (BNL, U Penn)
- 40 MHz ADC (Columbia)
- 10 Gbps Serializer (SMU)
- VCSEL array driver (SMU)



HASS Testing

- Custom test stands will be developed. Several stages of testing are planned.
 - Initial, single FEB testing: Powering, configuration and readout of individual chips, triggering readout of FEB.
 - Highly Accelerated Stress Screening (HASS): A test stand will be installed in an environmental chamber. Multiple FEBs at once will be subjected to a series of thermal cycles (verifies cold solder joints).



2005 HASS testing

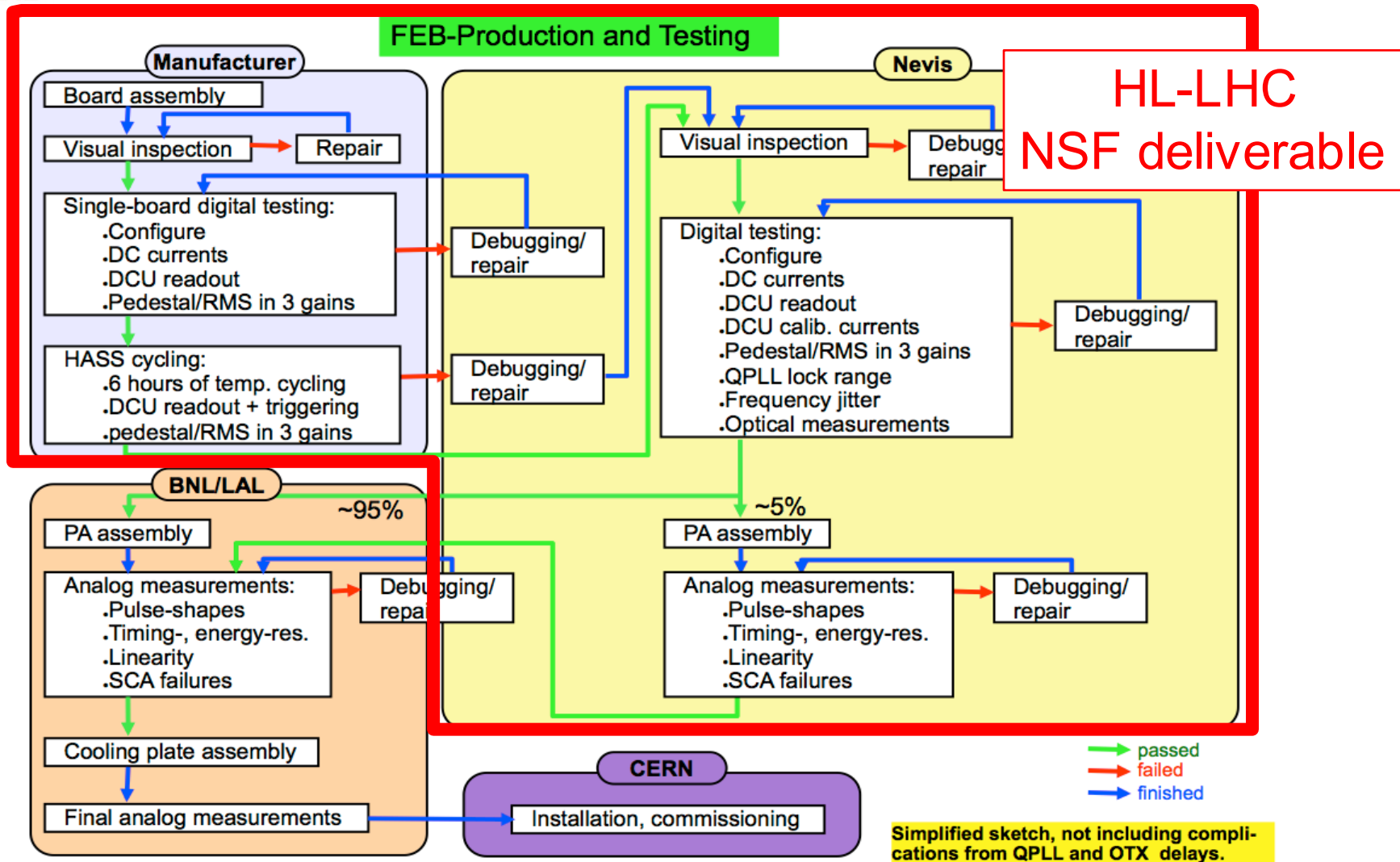


FEB Testing

- Parameters measured in original FEB testing.
- Anticipate a similar (where appropriate) table for FEB2.
- For FEB2 we will have clearly defined acceptance windows.
- Success is defined in-house, without need of external testing.

Parameter Type	Measurement	Units	Min. Value	Max. Value
Pedestals	Mean	ADC counts	880	1080
	RMS (w/o preamps)	ADC counts	0.5	1.5
Clock Quality	Jitter	ps	5	30
	Lower Edge of Lock Range	kHz	$f_{LHC} - 6$	$f_{LHC} - 2$
	Upper Edge of Lock Range	kHz	$f_{LHC} + 2$	$f_{LHC} + 6$
	Width of Lock Range	kHz	5	11
Optical Output Quality	Data-dependent Jitter	UI	0.01	0.18
	Average Optical Power	dBm	-10	-0.01
	Extinction Ratio Opt. Output	dB	10	30
DCU Quality	Current Source	μA	10	35
	Temperatures (uncalibrated)	degC	15	35
DCU Voltage Monitoring	3.3 V SCA VDDD	V	3.2	3.4
	3.3 V SCA VDDA	V	3.2	3.4
	2.5 V dig.	V	2.4	2.6
	-1.7 V SCA VSS	V	-1.875	-1.6
	3.0 V preamps	V	2.9	3.1
	-3.0 V shaper VSS	V	-3.3	-2.7
	4.5 V shaper VDD	V	4.40	4.65
Power Consumption	Current +6 V dig.	A	2.06	2.28
	Current +11 V (w/o preamps)	mA	2	7
	Current +6 V analog	A	4.23	4.53
	Current +4 V	A	2.6	2.9
	Current -4 V	A	4.84	5.36
	Total Power Dissipation	W	67.4	74.0

FEB Production - 2005

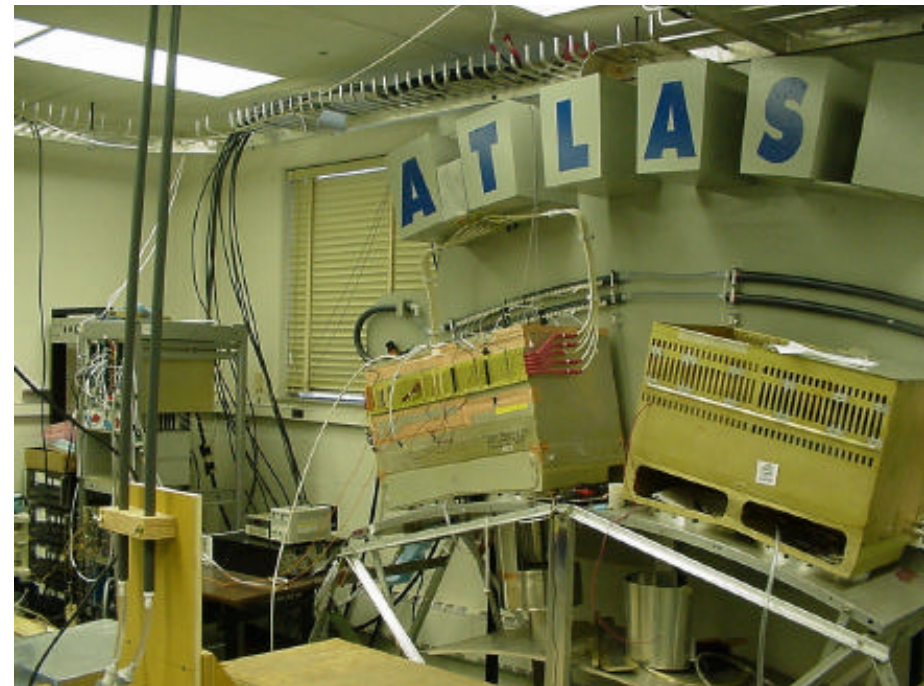


May 11th, 2005



System Integration: DOE Scope

- **Provide for informational purposes : DOE Scope.**
- Important to test all aspects of FEB2 in integrated system before launching production of 1600 boards.
 - Frontend Crate System Test, performed to validate the FE system integration and overall performance of the various FE crate boards (including FEB2)
 - Validation and final analog tests of 50% of the FEB2 boards
 - Integration and combined system test of FE and BE electronics
- **The equivalent tests were performed at BNL during the original ATLAS construction**





Summary

- Testing of ASICS and FEB2 critical for success of LAr electronics upgrade.
- Plans for testing ASICS (ADC) and FEB2:
 - Build on experience from original construction and Phase 1
 - Required little external input required (success defined and determined in house).
- University groups involved (Columbia, UT Austin) are experienced at ASIC and board testing, including from original construction and from Phase I upgrade.



Additional Material



Summary Cost Table

6.4.x.1 LAr FE Electronics						
WBS	Description	Labor FTE	Labor Ayk\$	M&S Ayk\$	Travel Ayk\$	TOTAL Ayk\$
6.4.x.1	LAr FE Electronics	34.9	5,370	4,948	95	10,414
	Instr. Physicists	5.6				
	Engineers	14.9				
	Techs	13.4				
	EE PhD Students	1.0				
6.4.1.1	LArFE_Columbia	29.9	4,947	4,816	55	9,818
	Instr. Physicists	5.6				
	Engineers	12.4				
	Techs	10.9				
	EE PhD Students	1.0				
6.4.2.1	LArFE_UTAustin	5.0	423	133	40	596
	Instr. Physicists	-				
	Engineers	2.5				
	Techs	2.5				
	EE PhD Students	-				



Cost Estimation

- Given the similarity of our HL-LHC deliverables to our previous ATLAS responsibilities, cost and manpower estimates are mostly based on our experience with either the original ATLAS construction project or the ongoing ATLAS Phase I upgrade project.
 - ASIC Testing: Estimated based on Phase 1 ADC development for LTDB.
 - FEB Testing: Estimated based on original FEB construction, and adjusted to reflect differences between FEB and FEB2 boards.



Glossary

- FEB – Front End Board for Liquid Argon (LAr) Calorimeter readout.
- Phase 1 - 2019-2020 detector upgrade installation (trigger path for LAr Calorimeter.
- HASS – Highly Accelerated Stress Screening